



Data Sheet

January 2002

2A, 80V and 100V, 1.050 Ohm, Logic Level, N-Channel Power MOSFETs

The RFP2N08L and RFP2N10L are N-Channel enhancement mode silicon gate power field effect transistors specifically designed for use with logic level (5V) driving sources in applications such as programmable controllers, automotive switching, and solenoid drivers. This performance is accomplished through a special gate oxide design which provides full rated conductance at gate biases in the 3V to 5V range, thereby facilitating true on-off power control directly from logic circuit supply voltages.

Formerly developmental type TA0924.

Ordering Information

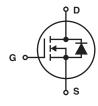
PART NUMBER	PACKAGE	BRAND		
RFP2N08L	TO-220AB	RFP2N08L		
RFP2N10L	TO-220AB	RFP2N10L		

NOTE: When ordering, include the entire part number.

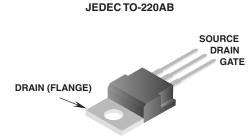
Features

- 2A, 80V and 100V
- r_{DS(ON)} = 1.050Ω
- Design Optimized for 5V Gate Drives
- Can be Driven Directly from QMOS, NMOS, TTL Circuits
- · Compatible with Automotive Drive Requirements
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device
- Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol



Packaging



Absolute Maximum Ratings $T_C = 25^{\circ}C$, Unless Otherwise Specified

	RFP2N08L	RFP2N10L	UNITS
Drain to Source Voltage (Note 1)	80	100	V
Drain to Gate Voltage (R _{GS} = 1M Ω) (Note 1) V _{DGR}	80	100	V
Continuous Drain Current I _D	2	2	А
Pulsed Drain Current (Note 3)	5	5	А
Gate to Source Voltage	±10	±10	V
Maximum Power Dissipation	25	25	W
Derate above 25°C	0.2	0.2	W/oC
Operating and Storage Temperature	-55 to 150	-55 to 150	°C
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10sT _L Package Body for 10s, See Techbrief 334T _{pkg}	300 260	300 260	°C O°

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}C$ to $125^{\circ}C$.

PARAMETER	SYMBOL	SYMBOL TEST CONDITIONS		TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	$V_{GS} = 0V, I_D = 250\mu A$				
RFP2N08L				-	-	V
RFP2N10L			100	-	-	V
Gate to Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	-	2.0	V
Gate to Source Leakage	I _{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$	-	-	±100	nA
Zero to Gate Voltage Drain Current	I _{DSS}	V_{DS} = Rated BV _{DSS} , V_{GS} = 0V	-	-	1.0	μA
		$V_{DS} = 0.8 \text{ x} \text{ Rated BV}_{DSS}, V_{GS} = 0 \text{V}, T_{C} = 125^{\circ}\text{C}$		-	25	μA
Drain to Source On Voltage (Note 2)	V _{DS(ON)}	I _D = 2A, V _{GS} = 5V		-	2.1	V
Drain to Source On Resistance (Note 2)	rDS(ON)	$I_D = 2A, V_{GS} = 5V$, (Figures 6, 7)		-	1.050	Ω
Turn-On Delay Time	t _{d(ON)}	$I_D = 2A, V_{DD} = 50V, R_G = 6.25\Omega,$		10	25	ns
Rise Time	t _r	R _L = 25Ω, V _{GS} = 5V (Figures 10, 11, 12)	-	15	45	ns
Turn-Off Delay Time	t _{d(OFF)}		-	25	45	ns
Fall Time	t _f		-	20	25	ns
Input Capacitance	C _{ISS}	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$ (Figure 9)		-	200	pF
Output Capacitance	C _{OSS}			-	80	pF
Reverse Transfer Capacitance	C _{RSS}			-	35	pF
Thermal Resistance Junction to Case	R _{θJC}		-	-	5	°C/W

Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

Source to Drain Diode Specifications

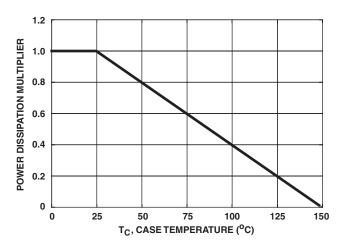
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	ТҮР	МАХ	UNITS
Source to Drain Diode Voltage (Note 2)	V _{SD}	I _{SD} = 2A	-	-	1.4	V
Reverse Recovery Time	t _{rr}	$I_{SD} = 2A$, $dI_{SD}/dt = 50A/\mu s$	-	100	-	ns

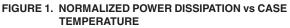
NOTES:

2. Pulse test: pulse width \leq 300µs, duty cycle \leq 2%.

3. Repetitive rating: pulse width limited by maximum junction temperature.

Typical Performance Curves Unless Otherwise Specified





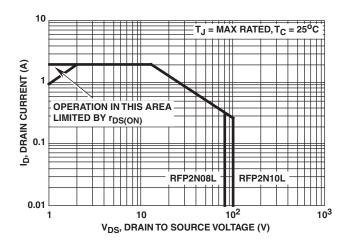


FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

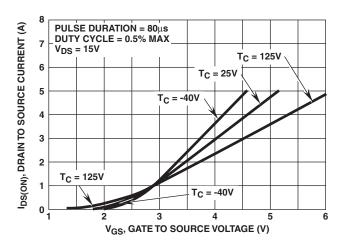


FIGURE 5. TRANSFER CHARACTERISTICS

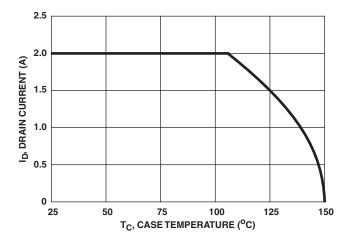
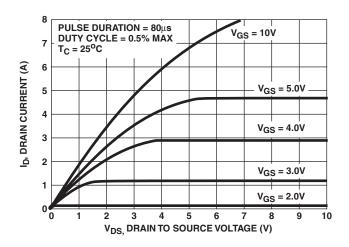


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE





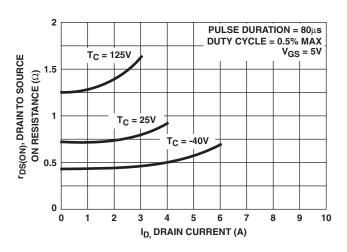
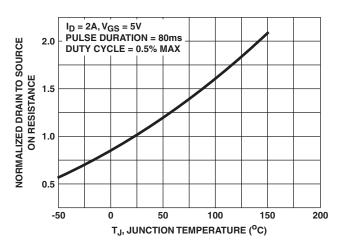


FIGURE 6. DRAIN TO SOURCE ON RESISTANCE vs DRAIN CURRENT

Typical Performance Curves Unless Otherwise Specified (Continued)





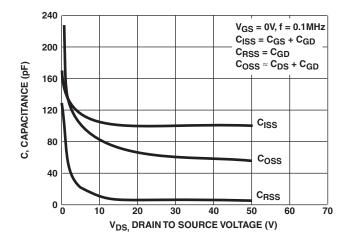
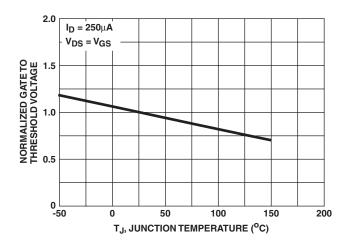
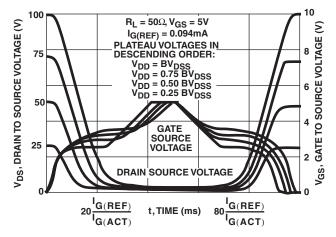


FIGURE 9. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE







NOTE: Refer to Fairchild Application Notes AN7254 and AN7260. FIGURE 10. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

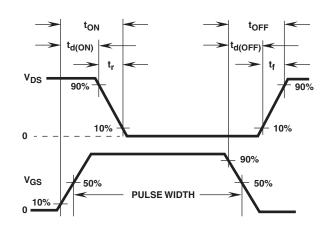


FIGURE 12. RESISTIVE SWITCHING WAVEFORMS

Test Circuit and Waveforms

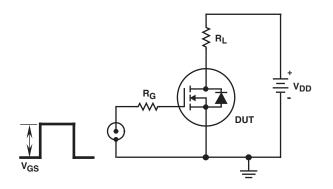


FIGURE 11. SWITCHING TIME TEST CIRCUIT

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